

2-15-06

02-24-2006



103184752

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)**

Meng-Chi HUNG  
Shang-Yung HOU  
Shin-Puu JENG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) (1-2) Oct. 28, 2003; (3) Oct. 29, 2003

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

**2. Name and address of receiving party(ies)**

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address:

Street Address: No. 8, Li-Hsin Rd. 6

Science-Based Industrial Park

City: Hsin-Chu

State:

Country: Taiwan, R.O.C. Zip: 300-77

Additional name(s) & address(es) attached? ☐ Yes ☒ No

**4. Application or patent number(s):**

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

02/17/2006 FFANAEIA 00000056 11354795

05 FC:8021

40.00 OP

Additional numbers attached? ☐ Yes ☒ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Daniel R. McClure

Internal Address: Thomas, Kayden, Horstemeyer &  
Risley, LLP

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Suite 1750

City: Atlanta

State: Georgia Zip: 30339

Phone Number: 770-933-9500

Fax Number: 770-951-0933

Email Address: dan.mcclure@tkhr.com

**6. Total number of applications and patents involved: 1**

**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

- ☒ Authorized to be charged by credit card  
☐ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers 1009  
Expiration Date 07/09

b. Deposit Account Number

Authorized User Name

**9. Signature:**

*Daniel R. McClure*  
Signature

Feb 15, 2006  
Date

Daniel R. McClure  
Name of Person Signing

Total number of pages including cover  
sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

11/354795  
021506

# ASSIGNMENT

WHEREAS, Meng-Chi HUNG, Shang-Yung HOU, Shin-Puu JENG,  
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as  
described and set forth in the below identified application for United States Letters  
Patent:

Title: BONDING PAD STRUCTURE  
Filed: October 29, 2003 Serial No. \_\_\_\_\_  
Executed on: October 28, 2003 and October 29, 2003

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of  
No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu,  
Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of  
acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters  
Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for  
good and valuable consideration, receipt of which is hereby acknowledged by Assignor,  
Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and  
transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights,  
title and interest in and to the said invention and application and all future improvements  
thereon, and in and to any Letters Patent which may hereafter be granted on the same in the  
United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively  
as it would have been held and enjoyed by said Assignor had this Assignment and transfer not  
been made, to the full end and term of any Letters Patent which may be granted thereon, or of  
any division, renewal, continuation in whole or in part, substitution, conversion, reissue,  
prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said  
Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said  
application and/or applications, execute, verify, acknowledge and deliver all such further  
papers, including applications for Letters Patent and for the reissue thereof, and instruments of  
assignment and transfer thereof, and will perform such other acts as Assignee lawfully may  
request, to obtain or maintain Letters Patent for said invention and improvement, and to vest  
title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the  
date(s) indicated.

Meng-Chi HUNG  
Meng-Chi HUNG

10/28/2003  
Date:

Shang-Yung HOU  
Shang-Yung HOU

10/28/2003  
Date:

SL3  
Shin-Puu JENG

10/29/2003  
Date:

TSMC2003-0866/0503-9728US

RECORDED: 02/15/2006

PATENT  
REEL: 017593 FRAME: 0057